L Number	Hits	Search Text	DB	Time stamp
1	8650336	(chip die semiconductor device dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:41
2	1110389	(stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:44
3	2293487	lead leadframe (lead adj frame)((stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit)))) same ((stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:43
4	1415780	lead leadframe (lead adj frame) same ((stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:43
5	42778	(lead leadframe (lead adj frame)) same ((stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:46
6	26290	(lead leadframe (lead adj frame)) with ((stack stacked stacking stackable plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:44
7	19666	(stack stacked stacking stackable) with (plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:45
8	42728	(stack stacked stacking stackable) same (plurality multi multiple level) same ((chip die semiconductor device dice ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:45
10	1244	(lead leadframe (lead adj frame)) same ((stack stacked stacking stackable) with (plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:46
11	739	(lead leadframe (lead adj frame)) with ((stack stacked stacking stackable) with (plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:46
9	1244	(lead leadframe (lead adj frame)) same ((stack stacked stacking stackable) with (plurality multi multiple level) with ((chip die semiconductor device dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/27 08:47